

50V NPN PRE-BIASED (R1=R2) SMALL SIGNAL TRANSISTOR IN DFN1006

Product Summary

Part Number	R1(NOM)	R2(NOM)	Marking
DDTC144ELP	47kΩ	47kΩ	N6

Features

- Epitaxial Planar Die Construction
- Complementary PNP Type Available (DDTA144ELP)
- Ultra-Small Leadless Surface Mount Package
- Ideally Suited for Automated Assembly Processes
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

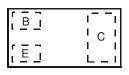
Mechanical Data

- Case: X1-DFN1006-3
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Marking Information
- Terminals: Finish NiPdAu
 Solderable per MIL-STD-202, Method 208@4
- Weight: 0.001 grams (Approximate)

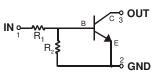
X1-DFN1006-3



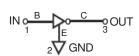
Bottom View



Top View Pin-Out



Device Symbol



Equivalent Inverter Circuit

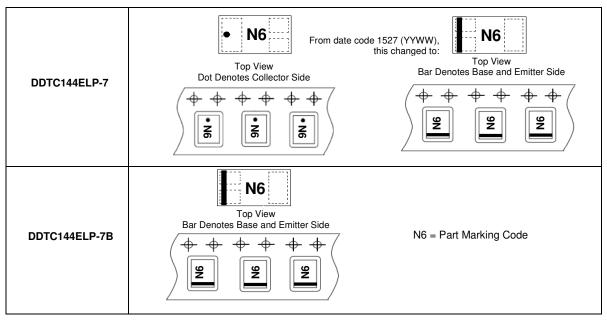
Ordering Information (Note 4)

Part Number	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
DDTC144ELP-7	N6	7	8	3,000
DDTC144ELP-7B	N6	7	8	10,000

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information





Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Supply Voltage	V _{CC}	50	V
Input Voltage	V _{IN}	-10 to +40	V
Output Current	I _{C(MAX)}	100	mA

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P_{D}	250	mW
Power Deration above 25°C	P _{der}	2	mW/°C
Thermal Resistance, Junction to Ambient Air (Note 5)	$R_{ hetaJA}$	500	°C/W
Operation and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV _{CBO}	50	_	_	V	$I_C = 50\mu A, I_E = 0$
Collector-Emitter Breakdown Voltage (Note 6)	BV _{CEO}	50	_	_	V	$I_C = 1.0 \text{mA}, I_B = 0$
Collector-Base Cut Off Current	I _{CBO}	_		0.5	μΑ	$V_{CB} = 50V, I_E = 0$
Input Voltage (Note 6)	$V_{I(OFF)}$	0.5	1.2	_	V	$V_{CE} = 5V, I_{O} = 100 \mu A$
Imput voitage (Note 6)	$V_{I(ON)}$	_	1.6	3]	$V_{CE} = 0.3V, I_{O} = 2mA$
Output Voltage (Note 6)	V _{O(ON)}	_	_	0.3	V	$I_{O}/I_{I} = 10 \text{mA}/0.5 \text{mA}$
Input Current	I _I	_	_	0.18	mA	$V_I = 5V$
Output Current	I _{O(OFF)}	_		0.5	μΑ	$V_{CC} = 50V, V_{I} = 0V$
DC Current Gain (Note 6)	G ₁	68	_	_	_	$V_{O} = 5V, I_{O} = 5mA$
Input Resistance	R ₁	32.9	47	61.1	kΩ	_
Resistance Ratio	R ₂ /R ₁	0.8	1	1.2	_	_
Transition Frequency (Note 7)	f⊤	_	250	_	MHz	$V_{CE} = 10V$, $I_{E} = 5mA$, $f = 100MHz$

Notes:

^{5.} For the device mounted on minimum recommended pad layout 1oz copper that is on a single-sided 1.6mm FR4 PCB; device is measured under still air conditions whilst operating in steady state condition. The entire exposed collector pad is attached to the heatsink.

6. Measured under pulsed conditions. Pulse width ≤ 300µs. Duty cycle ≤ 2%.

7. Characteristics of transistor only.



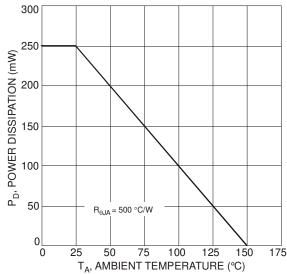


Fig. 1 Power Dissipation vs. Ambient Temperature

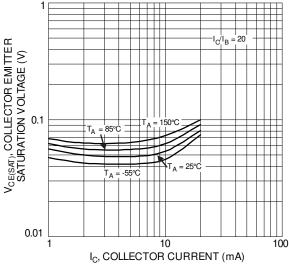
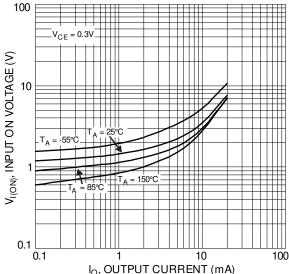


Fig. 3 Typical Collector Emitter Saturation Voltage vs. Collector Current



I_O, OUTPUT CURRENT (mA) Fig. 5 Typical Input ON Voltage vs. Output Current

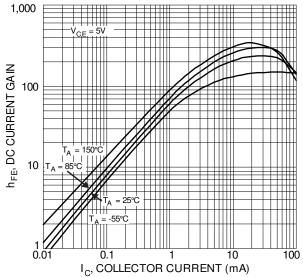
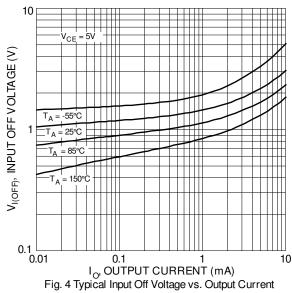


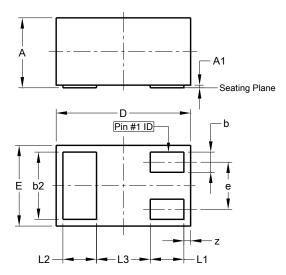
Fig. 2 Typical DC Current Gain vs. Collector Current





Package Outline Dimensions

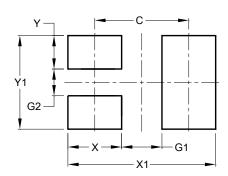
Please see http://www.diodes.com/package-outlines.html for the latest version.



X1-DFN1006-3				
Dim	Min	Max	Тур	
Α	0.47	0.53	0.50	
A1	0.00	0.05	0.03	
b	0.10	0.20	0.15	
b2	0.45	0.55	0.50	
D	0.95	1.075	1.00	
E	0.55	0.675	0.60	
е	ı	-	0.35	
L1	0.20	0.30	0.25	
L2	0.20	0.30	0.25	
L3	-	-	0.40	
Z	0.02	0.08	0.05	
All Dimensions in mm				

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.



Dimensions	Value (in mm)
C	0.70
G1	0.30
G2	0.20
Х	0.40
X1	1.10
Y	0.25
Y1	0.70



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